EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5025	382/149,145,224,159,100,141,155,181.CCLS.	USPAT	OR	ON	2009/06/29 11:58
L2	4478	715/774,835,837,764,841,210,839,762,809,804,973,250,866,708.CCLS.	USPAT	OR	ON	2009/06/29 12:01
L3	1453	719/310,315.CCLS.	USPAT	OR	ON	2009/06/29 12:01
L4	355	714/E11.21.CCLS.	USPAT	OR	ON	2009/06/29 12:02
L5	1846	356/237.1,237.2.CCLS.	USPAT	OR	ON	2009/06/29 12:03
L6	834	702/35,1,33.CCLS.	USPAT	OR	ON	2009/06/29 12:04
L7	599018	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:29
L8	125	L7 and user adj select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:32
L9	3	L8 and input adj user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:34
L10	4	L8 and input and user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:37
L11	4	L8 and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:55

L12	1	L8 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:58
L13	11	automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
L14	10	L13 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
L15	1	L14 and user adj select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
L16	1	L14 and user adj select$3 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
L17	3	automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and (illumination or source or light or optimal adj intensity or light adj intensity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:12
L18	3	automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:16
L19	0	L18 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:17
L21	781	L1 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 13:19
L22	3	L21 and user adj select$3 and review and data adj file	USPAT	OR	ON	2009/06/29 13:19

L23	27	L21 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:20
L24	0	L23 and input and user and page and learning adj mode and parameters	USPAT	OR	ON	2009/06/29 13:21
L26	0	L23 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:23
L27	0	L23 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:24
L28	2	L23 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 13:25
L29	2	L28 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 13:28
L30	0	L28 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:32
L31	0	L28 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:43
L32	0	L28 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)and(detect$3 or determining)and(defect or flaw or fault)	USPAT	OR	ON	2009/06/29 13:46
L33	18	L2 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 13:48
L34	4	L33 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:48
L35	0	L34 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 13:48
L36	0	L34 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:52
L37	2	L3 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 13:53
L38	0	L37 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 13:55

L39	0	L37 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:56
L40	0	L37 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:56
L41	2	L3 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 13:59
L42	1	L4 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 13:59
L43	0	L42 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 13:59
L44	0	L42 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:59
L45	0	L42 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:00
L46	733	L5 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 14:01
L47	5	L46 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 14:01
L48	0	L47 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:01
L49	0	L47 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:01
L50	5	L47 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 14:02
L51	0	L47 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:03
L52	599018	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L53	83	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04

L54	19	L53 and (wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L55	12	L54 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L56	3	L55 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L57	685554	L56 and select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L58	18	L53 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L59	17	L58 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L60	2	L52 and L53 and L57 and L59	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
L61	0	L60 and @ad<"20030712"	USPAT	OR	ON	2009/06/29 14:04
L63	129	L6 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	USPAT	OR	ON	2009/06/29 14:06
L64	4	L63 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:06
L65	0	L64 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:07

L66	0	L64 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 14:08
L67	3	L64 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 14:09
L68	0	L67 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:23
L69	1	L63 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 14:26
L70	0	L69 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:26
L71	0	L69 and user adj select$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:28
L79	1	((wafer$1 or semicondudor$l or chip$l or subtrat$1)and user adj select$3 and review and data adj file and input and user and page and learning adj mode).clm.	US-PGPUB	OR	ON	2009/06/29 14:51
L81	1	L69 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3 or accept$3)	USPAT	OR	ON	2009/06/29 14:55
L82	0	L81 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and(detect$3 or determining)and(defect or flaw or fault)and (assign$3 or test$3 or evaluat$3)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:59
L83	0	L81 and select$3 adj(wafer$1 or semicondudor$l or chip$l or substrat$1)and(capturing or pictures or ccd or camera)and(detect$3 or determining)and(defect or flaw or fault)and (assign$3 or test$3 or evaluat$3)and align$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:59
S1	571947	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:27
S2	1	S1 and automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:29
S3	1	automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30

S4	1	S1 and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S5	1	defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S6	2	defect adj classification and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S7	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S8	19	S7 and (wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S9	17	S8 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
S10	12	S8 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
S11	24	((DIRK) near2 (SOENKSEN)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:36
S12	11	((RALF) near2 (FRIEDRICH)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S13	1	((ANDREAS) near2 (DRAEGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S14	2	((DETLEF) near2 (SCHUPP)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37

S16	2	((THIN) near2 ("VAN LUU")).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
S17	3	((WOLFGANG) near2 (LANGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
S18	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S19	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S20	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S21	0	S12 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S22	0	S13 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:43
S23	3	S10 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:46
S24	638382	S23 and select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47
S25	0	S23 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47

S26	18	S7 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:48
S27	0	S26 and parameters and learning adj node	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S28	0	S26 and parameters and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S29	17	S26 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S30	2	S1 and S7 and S24 and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
S31	2	S30 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
S32	18	S7 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:57
S33	16	S32 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:58
S34	20	S1 and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:00

S35	638382	S34 and select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:01
S36	4	S34 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:33
S37	1	S34 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S38	0	S37 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S39	16	S34 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S40	0	S39 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S41	2	S39 and learning	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S42	16	S26 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:39
S43	0	S42 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40

S44	0	S42 and learning near mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
S45	0	S42 and learning near3 mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
S46	11	S42 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
S47	598	S1 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:44
S48	340	S47 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:44
S49	1	S48 and input and user and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:45
S50	1	S48 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:46
S51	4	S48 and alignment adj procedure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:46
S52	0	S8 and automatic adj defect and recognition and(detect$3 or determining)same (defect or flaw or fault)same(assign$3 or test$3 or evaluat$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02

S53	0	S48 and automatic adj defect and recognition and(detect$3 or determining)same (defect or flaw or fault)same(assign$3 or test$3 or evaluat$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
S54	1	automatic adj defect and recognition and(detect$3 or determining)same (defect or flaw or fault)same(assign$3 or test$3 or evaluat$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
S55	11	automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S56	5	S55 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S57	1	S56 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
S58	0	S57 and edit adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05
S59	0	S57 and edit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05
S60	0	S57 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:07
S61	1	S57 and circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:07

S62	0	S61 and logic adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:08
S63	0	S61 and blank adj wafer$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:08
S64	1	S56 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 14:02
S65	571947	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:12
S66	2	S65 and select$3 and review adj data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
S67	2	S65 and review adj data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
S68	638	S65 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
S69	134	S65 and review same data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
S70	0	S69 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15

S71	0	S69 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S72	1	S69 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S73	11	S68 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S74	5	S73 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S75	5	S74 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S76	1	S75 and (user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
S77	1	S75 and (user or operator or human)and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
S78	9	S68 and(detect$3 or determining) and (defect or fault or flaw)and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:19
S79	13	learning and(knowledge-based or knowledge adj based)and database and automatic and defect adj classification	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21

S80	10	S79 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S81	0	S80 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S82	1	S80 and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:22
S83	8	S80 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S84	8	S83 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S85	6	S84 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:43
S86	5	S84 and descriptor adj (defect or fault or flaw)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:46
S87	573639	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:04
S88	19	S87 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05

S89	640949	S88 and select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
S90	2	S88 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
S91	8	S87 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
S92	2	S91 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
S93	0	S92 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:15
S94	8	S91 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:27
S95	1	S94 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:29
S96	2	S92 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30
S97	2	S96 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30

S98	0	S97 and circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:31
S99	0	S97 and defect and (classification or classifier or classify)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:32
S100	0	S97 and(classification or classifier or classify or grouping)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:33
S101	0	S97 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:33
S102	2	S97 and (intensity or contrast or brightness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
S103	2	S102 and(illumination or source or light)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
S104	2	S103 and(blank adj wafer$1 or wafer$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:36
S105	2	S104 and(polymer or layer or oxide adj layer or contact or metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:38
S106	0	S105 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:39

S107	0	S105 and focus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:39
S108	0	S105 and magnificat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
S109	2	S105 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
S110	2	S109 and select$3 adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:41
S111	2	"6973209".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
S112	0	S111 and alignment	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
S113	1	S111 and align$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
S114	0	S111 and align$3 same light	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:41
S115	1	S111 and align$3 and(light or source or illuminat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:41

S116	1	S115 and adjusting	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
S117	0	S116 and optimal adj intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
S118	1	S116 and optimal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
S119	0	S118 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
S120	1	S118 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:43
S121	1	S120 and algorithm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:46
S122	1	S121 and automatic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47
S123	0	S122 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47
S124	1	S122 and (intensity or contrast or brightness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47

S125	0	S124 and text adj image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:48
S126	0	S124 and text	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:48
S127	1	S124 and recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S128	0	S127 and review	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S129	1	S127 and dictionary	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S130	1	S129 and registered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:50
S131	1	S130 and drag	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:51
S132	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S133	18	S132 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09

S134	16	S133 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S135	0	S132 and select$3 same review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
S136	5	S132 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
S137	3	S136 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:14
S138	1	S137 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:19
S139	0	S137 and defect adj descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:20
S140	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44
S141	5	S140 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44
S142	3	S141 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44

S143	2	S142 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:45
S144	3	"6408219".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:46
S145	1	S144 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:47
S146	1	S144 and select$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:48
S147	732	select$3 same review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
S148	62	S147 and(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
S149	0	S148 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
S150	0	S148 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
S151	14	S148 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51

S152	0	S151 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51
S153	0	S151 and display and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
S154	0	S151 and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
S155	0	S151 and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:12
S156	0	S151 and select$3 adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:13
S157	1	S151 and align$3 and(light or source or illuminat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:13
S158	0	S157 and(user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
S159	0	S157 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
S160	0	S157 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:36

S161	11	automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
S162	5	S161 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
S163	1	S162 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
S164	0	S163 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
S165	575216	(wafer$1 or semicondudor$l or chip$l or subtrat$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
S166	10	S165 and automatic adj defect and recognition and(detect$3 or determining)and(defect or flaw or fault)and(assign$3 or test$3 or evaluat$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59
S167	643423	S166 and select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59
S168	1	S166 and select$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00
S169	0	S168 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00

S170	1	S166 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00
S171	0	S170 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S172	4	S166 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S173	0	S172 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S174	7745	S165 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S175	2341	S174 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S176	775	S175 and logic adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02
S177	9	S176 and blank adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02
S178	8	S177 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03

S179	0	S178 and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
S180	0	S178 and photo adj resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
S181	0	S178 and polymer adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S182	51765	polymer adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S183	33269	S182 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
S184	2388	S183 and oxide adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
S185	1703	S184 and contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
S186	16332	S183 and contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
S187	10	S186 and metal adj later	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06

S188	1	S187 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
S189	1	S188 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
S190	1	S189 and(intensity or contrast or brightness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
S191	0	S190 and align$3 and(light or source or illuminat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
S192	1	S190 and(light or source or illuminat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
S193	0	S192 and magnificat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
S194	0	S192 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
S195	0	S192 and histogram	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
S196	0	S195 and focus$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:12

S197	51832	polymer adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S198	33269	S197 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S199	16332	S198 and contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S200	10	S199 and metal adj later	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S201	1	S200 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S202	1	S201 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S203	1	S202 and(intensity or contrast or brightness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S204	1	S203 and(light or source or illuminat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S205	0	S204 and metal adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:05

S206	1	S204 and metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:06
S207	0	S206 and bright adj field	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
S208	0	S206 and bright	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
S209	1	S206 and (UV or DUV)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:08
S210	0	S209 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:08
S211	0	S209 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:09
S212	1	S209 and contrast	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:10
S213	0	S212 and histogram	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:10
S214	795256	select$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:12

S215	2665	S214 and polymer adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S216	12	S215 and bright adj field	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S217	9	S216 and (UV or DUV)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S218	3	S217 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S219	3	S218 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S220	0	S219 and histogram	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S221	0	S219 and metal adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S222	0	S219 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S223	4	S216 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15

| S224 | 0 | S223 and @ad< "20030712" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/01/02 14:15 |
| S225 | 0 | S223 and @ad< "20030712" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/01/02 14:15 |

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